

SID

Factory: Rot am See

Article:

495

ML4

Provided:

Kracht, Enrico

Customer:

Date:

29.07.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	A00 B00
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	315		2	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		4	
B-RS-FR4-DS-1.20mm-035+035-TG150-HF	50200786	35	L2		
		1130		5	
		35	L3		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	315		6	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		7	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		8	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	9	

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1900 µm

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